

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	KEIGO YASUDA	09/14/2021
RECEIVING PARTY DATA		
Name:	FUTABA INDUSTRIAL CO., LTD.,	
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PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	17475821
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DATE SIGNED:	09/16/2021	
Total Attachments: 3		
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ASSIGNMENT

This Assignment made by **Keigo Yasuda**, being a citizen of Japan and having a correspondence address of c/o FUTABA INDUSTRIAL CO., LTD., 1, Aza-ochaya, Hashime-cho, Okazaki-shi, Aichi 444-8558 Japan;

WITNESSETH: That,

WHEREAS, I believe I am the original inventor of one or more inventions described in Japanese Patent Application No. 2020-157895, filed on September 18, 2020 and in a corresponding U.S. patent application filed or to be filed entitled **METHOD OF RESISTANCE SPOT WELDING AND RESISTANCE SPOT WELDING APPARATUS**, and whereas I authorize representatives of the Nagoya International Patent Firm (having a principal place of business in Japan) and its appointed agents to enter the following information identifying such U.S. patent application when known: U.S. Patent Application No. 17/475,821 filed on September 15, 2021 (with the foregoing Japanese and U.S. patent applications being collectively referred to as the Applications); and

WHEREAS, **FUTABA INDUSTRIAL CO., LTD.**, a corporation duly organized and existing under the laws of Japan and having a principal place of business at 1, Aza-ochaya, Hashime-cho, Okazaki-shi, Aichi 444-8558 Japan, hereinafter referred to as Assignee, is desirous of acquiring the entire right, title and interest in and to said invention(s) as described in the Applications, and any and all Letters Patent which shall be granted therefor;

NOW, THEREFORE, To All Whom It May Concern, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I hereby sell, assign, transfer and set over unto the Assignee, its successors and assigns, the entire right, title and interest in and to the invention(s) and the Applications and in and to any and all foreign patent

applications filed on the invention based on and claiming priority to any one of more applications of the Applications, and in and to any and all Letters Patent of the United States and foreign countries which may hereafter be granted therefor, and in any and to any and all continuations, continuations-in-part, substitutions, divisions or reissues of said Letters Patent, the same to be held and enjoyed by the Assignee, for its interest, and for its own use and behalf, and the use and behalf of its successors and assigns, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me had this assignment and sale not been made, and I hereby authorize and empower the Assignee, its successors, assigns or nominees to file applications for any Letters Patent or other form of protection on said invention(s) in its own name or in the name of its successor, assignee, or nominee, in any and all countries where it may desire to file such applications and where said applications may be filed by another than the inventor;

And for the consideration aforesaid, I hereby covenant and agree to and with the Assignee, its successors and assigns, that at the time of the execution and delivery of these presents that I am a lawful owner or joint owner of the entire right, title and interest in and to the invention(s), the Applications and Letters Patent above-mentioned and that the same are unencumbered, and that I have good right and lawful authority to sell and convey the same in the manner herein set forth;

And for the consideration aforesaid, I hereby covenant and agree to and with the Assignee, its successors and assigns, that I will, whenever its counsel or the counsel of its successors and assigns, learned in the law, shall advise that an amendment, division, continuation, continuation-in-part, or substitution of, or any other proceeding in connection with said application, including interference proceedings, is lawful and desirable, sign all papers and drawings, take all rightful oaths, and do all acts necessary or required to be done for the procurement of valid Letters Patent

for said invention(s), or for the reissue of the same without charge to the Assignee, its successors or assigns, but at its or their expense, and I hereby covenant and agree to sign all papers and drawings, take all rightful oaths, and do all acts necessary or required to be done for procurement of Letters Patent, or other form of protection, for said invention(s) in countries foreign to the United States, and for further investing or confirming the right and title therein to the Assignee, its successors, assignee, or nominee, without charge to the Assignee, its successor, assignee or nominee, but at its or their own expense;

I hereby request the Commissioner for Patents and other applicable patent authorities to issue the Letters Patent in accordance with this instrument;

IN WITNESS WHEREOF, I have hereunto set my hand and seal.

September 14, 2021

Date

安田 圭吾

Keigo Yasuda